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EXPEDITED PROCEDURE
RESPONSE UNDER 37 CFR 1.116
EXAMINING GROUP: 1722
BOX AF

DOCKET NO.: 4029

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN THE MATTER OF THE APPLICATION FOR PATENT

OF: Michio OSADA et al.

| Art Unit: 1722

SERIAL NO.: 09/705,237

| Confirmation No.: 4586

FILED: November 2, 2000

| EX.: Thukhanh T. Nguyen

FOR: Die Used for Resin-Sealing and
Molding an Electronic Component

OK to enter
TN 2/9/04

MS AF
COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

February 9, 2004

RESPONSE TO THE FINAL OFFICE ACTION OF DECEMBER 9, 2003 INCLUDING
AN ATTACHED COVER SHEET WITH CERTIFICATE OF TELEFAX TRANSMISSION

Dear Sir:

This Response should receive expedited handling because it is being filed within **TWO MONTHS** after the mailing date of the Final Office Action on December 9, 2003.

Please amend the above identified application as follows.

4029/WFF:ar

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